

CALCE Web Seminar
Predicting Plated Through Hole Life at Assembly and in the Field from Thermal Stress Data

Date and Time:

Jun. 20th start at 11:00am U.S. Eastern (8:00am U. S. Pacific)

Over the past ten years, two new test methods: Interconnect Stress Test [1] and Highly Accelerated Thermal Shock [2] have been developed to perform thermal cycling testing and in particular, to measure plated through hole reliability. Both of these test methods have proved useful in their ability to quantify plated through hole reliability and have gained a wide level of acceptance and creditability within the industry. Along with more traditional air-to-air and liquid-to-liquid thermal cycle methods, these two new test methods expand the test methods available to the interconnect industry. While the number of testing options for plated through hole thermal cycling has increased, there has been little work performed within the industry on developing methods to analyze and use the data coming from these new test methods.